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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HD74HC292/HD74HC294

Programmable Frequency Divider/Digital Timer

ADE-205-486 (Z)
1st. Edition
Sep. 2000

Description

This device divides the incoming clock frequency by a number (a power of 2) that is preset by the Programming inputs. It has two Clock inputs, either of which may be used as a clock inhibit. The device also has an active-low Reset, which initializes the internal flip-flop states. Test Point outputs (TP1, TP2, TP3) are provided with HD74HC292 to facilitate incoming inspections.

Test Point output is provided with HD74HC294 to facilitate incoming inspections.

Features

- High Speed Operation: t_{pd} (Clock to Q) = 16 ns typ (C_L = 50 pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: V_{CC} = 2 to 6 V
- Low Input Current: 1 μA max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μA max (Ta = 25°C)

Function Table

$\overline{CLR}$	CLK1	CLK2	Q Output Mode
L	X	X	Cleared to L
H	⎍	L	Count
H	L	⎍	Count
H	H	X	Inhibit
H	X	H	Inhibit

HD74HC292

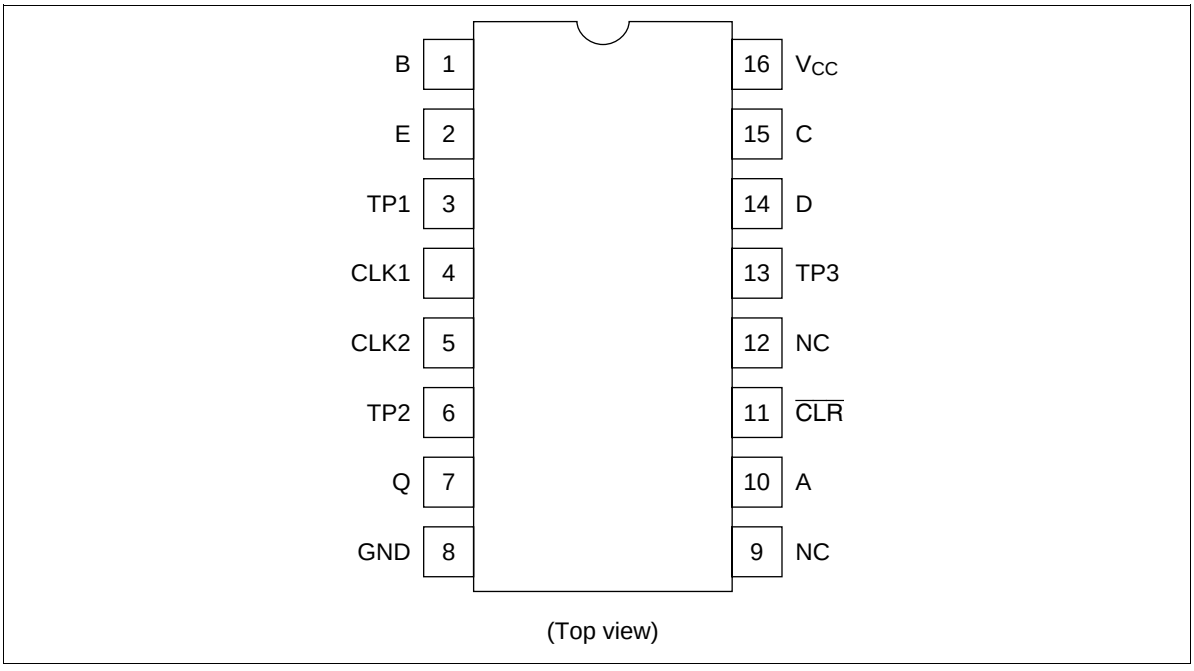
Programming Inputs					Frequency Division							
					Q Out		TP1		TP2		TP3	
E	D	C	B	A	Binary	Decimal	Binary	Decimal	Binary	Decimal	Binary	Decimal
L	L	L	L	L	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit
L	L	L	L	H	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit	Inhibit
L	L	L	H	L	2^2	4	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	L	L	H	H	2^3	8	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	L	H	L	L	2^4	16	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	L	H	L	H	2^5	32	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	L	H	H	L	2^6	64	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	L	H	H	H	2^7	128	2^9	512	2^{17}	131,072	2^{24}	16,777,216
L	H	L	L	L	2^8	256	2^9	512	2^{17}	131,072	2^2	4
L	H	L	L	H	2^9	512	2^9	512	2^{17}	131,072	2^2	4
L	H	L	H	L	2^{10}	1,024	2^9	512	2^{17}	131,072	2^4	16
L	H	L	H	H	2^{11}	2,048	2^9	512	2^{17}	131,072	2^4	16
L	H	H	L	L	2^{12}	4,096	2^9	512	2^{17}	131,072	2^6	64
L	H	H	L	H	2^{13}	8,192	2^9	512	2^{17}	131,072	2^6	64
L	H	H	H	L	2^{14}	16,384	2^9	512	Disabled LOW		2^8	256
L	H	H	H	H	2^{15}	32,768	2^9	512	Disabled LOW		2^8	256
H	L	L	L	L	2^{16}	65,536	2^9	512	2^3	8	2^{10}	1,024
H	L	L	L	H	2^{17}	131,072	2^9	512	2^3	8	2^{10}	1,024
H	L	L	H	L	2^{18}	262,144	2^9	512	2^5	32	2^{12}	4,096
H	L	L	H	H	2^{19}	524,288	2^9	512	2^5	32	2^{12}	4,096
H	L	H	L	L	2^{20}	1,048,576	2^9	512	2^7	128	2^{14}	16,384
H	L	H	L	H	2^{21}	2,097,152	2^9	512	2^7	128	2^{14}	16,384
H	L	H	H	L	2^{22}	4,194,304	Disabled LOW		2^9	512	2^{16}	65,536
H	L	H	H	H	2^{23}	8,388,608	Disabled LOW		2^9	512	2^{16}	65,536
H	H	L	L	L	2^{24}	16,777,216	2^3	8	2^{11}	2,048	2^{18}	262,144
H	H	L	L	H	2^{25}	33,554,432	2^3	8	2^{11}	2,048	2^{18}	262,144
H	H	L	H	L	2^{26}	67,108,864	2^5	32	2^{13}	8,192	2^{20}	1,048,576
H	H	L	H	H	2^{27}	134,217,728	2^5	32	2^{13}	8,192	2^{20}	1,048,576
H	H	H	L	L	2^{28}	268,435,456	2^7	128	2^{15}	32,768	2^{22}	4,194,304
H	H	H	L	H	2^{29}	536,870,912	2^7	128	2^{15}	32,768	2^{22}	4,194,304
H	H	H	H	L	2^{30}	1,073,741,824	2^9	512	2^{17}	131,072	2^{24}	16,777,216
H	H	H	H	H	2^{31}	2,147,483,648	2^9	512	2^{17}	131,072	2^{24}	16,777,216

HD74HC294

Programming Inputs				Frequency Division			
				Q Output		TP Output	
D	C	B	A	Binary	Decimal	Binary	Decimal
L	L	L	L	Inhibit	Inhibit	Inhibit	Inhibit
L	L	L	H	Inhibit	Inhibit	Inhibit	Inhibit
L	L	H	L	2^2	4	2^9	512
L	L	H	H	2^3	8	2^9	512
L	H	L	L	2^4	16	2^9	512
L	H	L	H	2^5	32	2^9	512
L	H	H	L	2^6	64	2^9	512
L	H	H	H	2^7	128		Disabled LOW
H	L	L	L	2^8	256	2^2	4
H	L	L	H	2^9	512	2^3	8
H	L	H	L	2^{10}	1,024	2^4	16
H	L	H	H	2^{11}	2,048	2^5	32
H	H	L	L	2^{12}	4,096	2^6	64
H	H	L	H	2^{13}	8,192	2^7	128
H	H	H	L	2^{14}	16,384	2^8	256
H	H	H	H	2^{15}	32,768	2^9	512

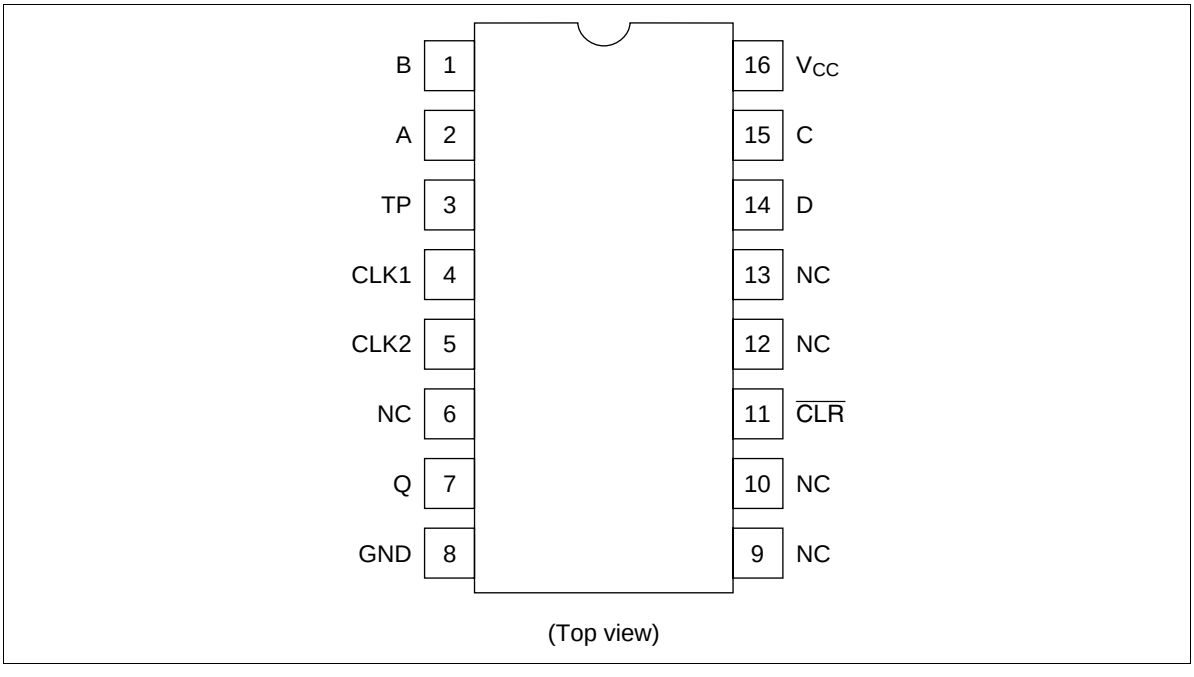
Pin Arrangement

HD74HC292



(Top view)

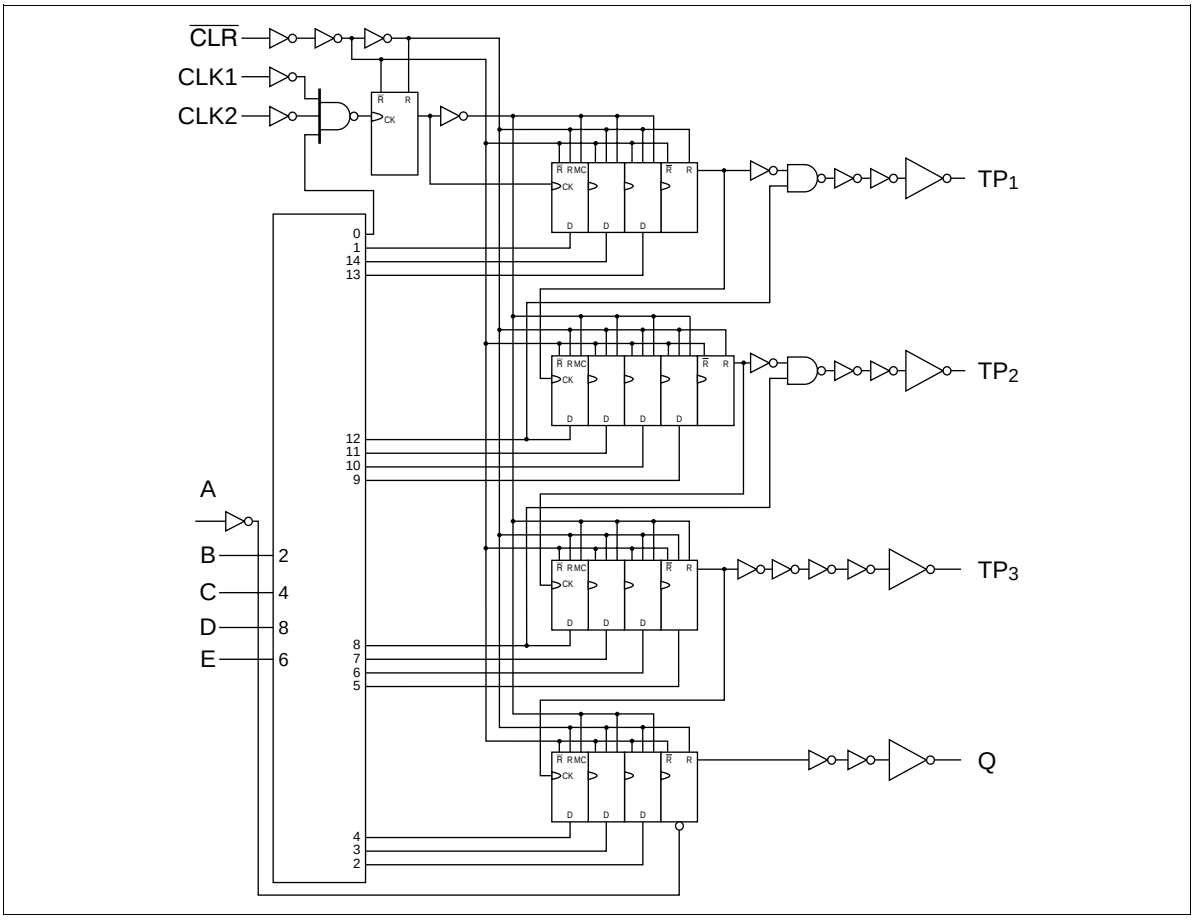
HD74HC294



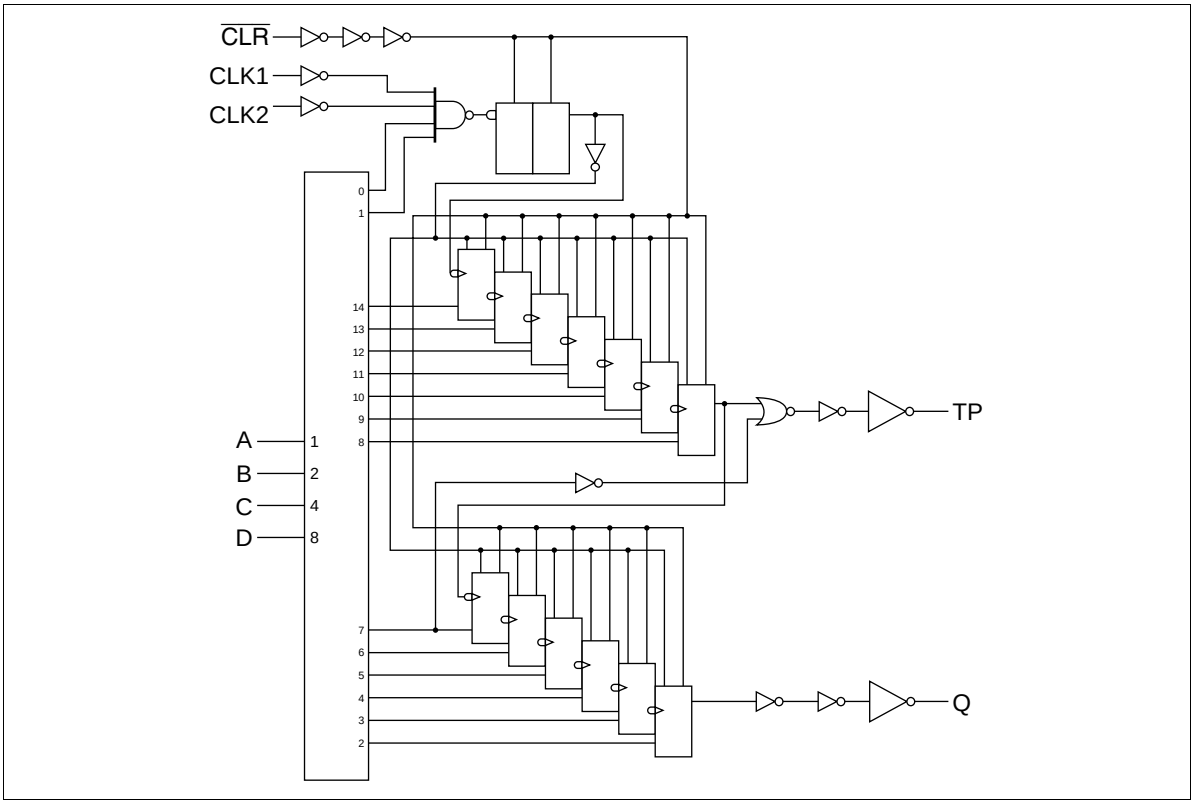
(Top view)

Logic Diagram

HD74HC292



HD74HC294



DC Characteristics

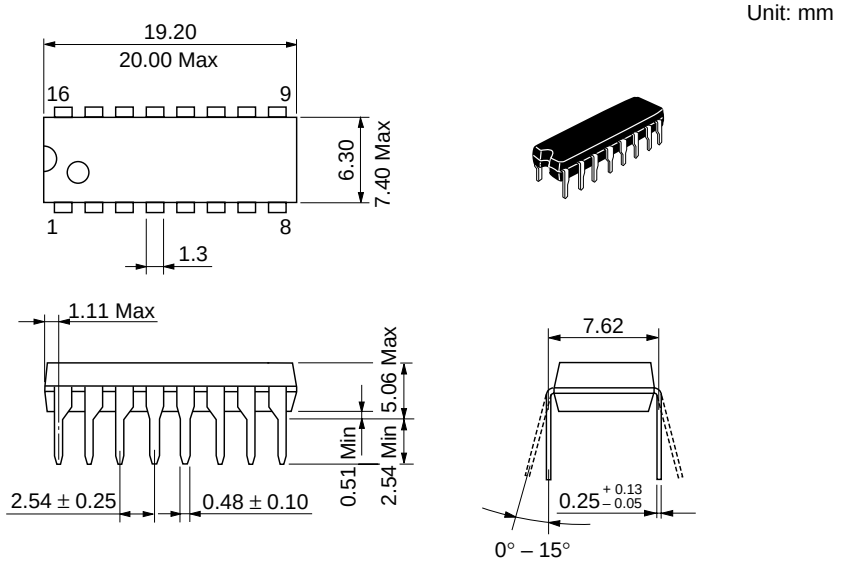
Item	Symbol	V_{CC} (V)	Ta = 25°C Min	Typ	Max	Ta = –40 to +85°C Min	Max	Unit	Test Conditions
Input voltage	V_{IH}	2.0	1.5	—	—	1.5	—	V	
		4.5	3.15	—	—	3.15	—		
		6.0	4.2	—	—	4.2	—		
	V_{IL}	2.0	—	—	0.5	—	0.5	V	
		4.5	—	—	1.35	—	1.35		
		6.0	—	—	1.8	—	1.8		
Output voltage	V_{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V_{IH} or V_{IL} I_{OH} = –20 µA
		4.5	4.4	4.5	—	4.4	—		
		6.0	5.9	6.0	—	5.9	—		
		4.5	4.18	—	—	4.13	—		I_{OH} = –4 mA
		6.0	5.68	—	—	5.63	—		I_{OH} = –5.2 mA
	V_{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V_{IH} or V_{IL} I_{OL} = 20 µA
		4.5	—	0.0	0.1	—	0.1		
		6.0	—	0.0	0.1	—	0.1		
		4.5	—	—	0.26	—	0.33		I_{OL} = 4 mA
		6.0	—	—	0.26	—	0.33		I_{OL} = 5.2 mA
Input current	Iin	6.0	—	—	±0.1	—	±1.0	µA	Vin = V_{CC} or GND
Quiescent supply current	I_{CC}	6.0	—	—	4.0	—	40	µA	Vin = V_{CC} or GND, Iout = 0 µA

AC Characteristics (C_L = 50 pF, Input $t_r = t_f$ = 6 ns)

			Ta = 25°C			Ta = –40 to +85°C			
Item	**Symbol**	**V_{cc} (V)**	**Min**	**Typ**	**Max**	**Min**	**Max**	**Unit**	**Test Conditions**
Maximum clock frequency	f_{max}	2.0	—	—	5	—	4	MHz	
		4.5	—	—	27	—	21		
		6.0	—	—	31	—	24		
Propagation delay time	t_{PLH}	2.0	—	—	600	—	750	ns	Clock to output
		4.5	—	16	120	—	150		
		6.0	—	—	100	—	125		
Removal time	t_{rem}	2.0	100	—	—	125	—	ns	
		4.5	20	–4	—	25	—		
		6.0	17	—	—	21	—		
Pulse width	t_w	2.0	80	—	—	100	—	ns	
		4.5	16	14	—	20	—		
		6.0	14	–	—	17	—		
Output rise/fall time	t_{TLH}	2.0	—	—	75	—	95	ns	
	t_{THL}	4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	Cin	—	—	5	10	—	10	pF	

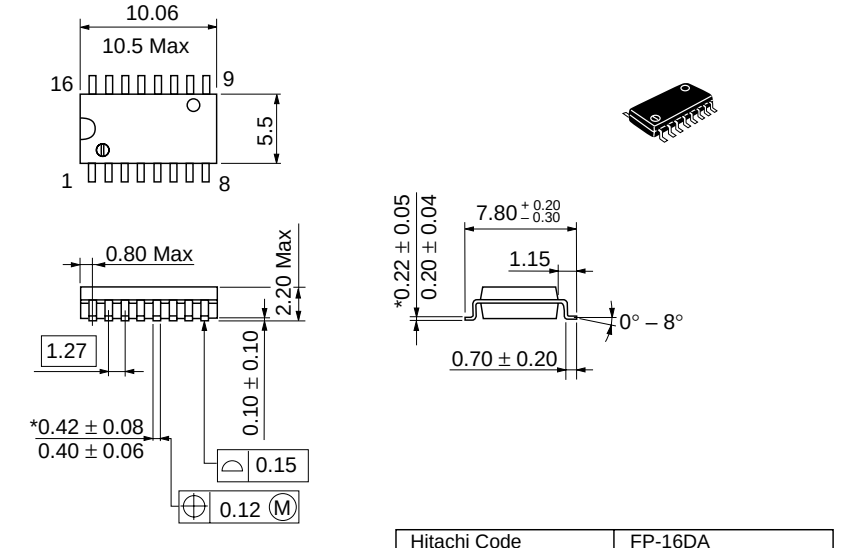
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

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